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PATENT APPLICATION

N THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q88153

Koji WATANABE, et al.

Appln. No.: 10/541,586

Group Art Unit: 1734

Confirmation No.: 1996

Examiner: Michael J. Feely

Filed: July 7, 2005

For: CURING RESIN COMPOSITION, ADHESIVE EPOXY RESIN PASTE, ADHESIVE

EPOXY RESIN SHEET, CONDUCTIVE CONNECTION PASTE, CONDUCTIVE

CONNECTION SHEET, AND ELECTRONIC COMPONENT JOINED BODY

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §§ 1.97 and 1.98

MAIL STOP AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

One copy of each of the listed documents is submitted herewith, except for U.S. patents and/or U.S. patent publications, together with a copy of a Supplementary European Search Report and Annex for counterpart European Application No. EP 03 78 6351 wherein the listed documents were cited.

INFORMATION DISCLOSURE STATEMENT

U.S. Appln. No.: 10/541,586

Attorney Docket No.: Q88153

The present Information Disclosure Statement is being filed before the mailing date of

the first Office Action on the merits, and therefore no Statement under 37 C.F.R. § 1.97(e) or fee

under 37 C.F.R. § 1.17(p) is required.

The present Information Disclosure Statement is being filed thirty days or fewer from the

communication from a foreign patent office and a Statement Under 37 C.F.R. §1.704(d) is

attached.

The submission of the listed documents is not intended as an admission that any such

document constitutes prior art against the claims of the present application. Applicant does not

waive any right to take any action that would be appropriate to antedate or otherwise remove any

listed document as a competent reference against the claims of the present application.

The USPTO is directed and authorized to charge all required fees, except for the Issue

Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any

overpayments to said Deposit Account.

Respectfully submitted,

SUGHRUE MION, PLLC

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WASHINGTON OFFICE

23373

Date: March 8, 2007

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STATEMENT UNDER 37 CFR § 1.704(d)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

The undersigned hereby states, upon information and belief:

That each item of information contained in the Information Disclosure Statement filed concurrently herewith was cited in a communication from a foreign patent office in a counterpart foreign application and that the communication was not received by any individual designated in 37 C.F.R. §1.56(c) more than thirty days prior to the filing of said Information Disclosure Statement.

Respectfully submitted,

SUGHRUE MION, PLLC

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Date: March 8, 2007

Substitute for Form 1449 A & B/PTO

STATEMENT BY APPLI

(use as many sheets as necessary)

Sheet	Ī	of	1	

Complete if Known				
Application Number	10/541,586			
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Filing Date	July 7, 2005			
First Named Inventor	Koji WATANABE			
Art Unit	1734			
Examiner Name	Michael J. Feely			
Attorney Docket Number	Q88153			

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cita	Document Number		Publication Date	
	Cite No.1	Number	Kind Code ² (if known)	MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		US 2002/0025431	A1	02-28-2002	Sawamura et al
		US 5,686,509		11-11-1997	Nakayama et al
		US			

FOREIGN PATENT DOCUMENTS							
	Cite	Foreign Patent Document			Publication Date	Name of Patentee or	
	No.1	Country Code ³	Number ⁴	Kind Code ⁵ (if known)	MM-DD-YYYY	Applicant of Cited Document	Translation ⁶
		ЕР	0 914 027	A1	05-06-1999	HITACHI CHEMICAL COMPANY, LTD	
		EP	1 160 857	A2	12-05-2001	SONY CHEMICALS CORP.	
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NON PATENT LITERATURE DOCUMENTS					
Examiner Cite Initials* No.1		Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.			
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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Applicant's unique citation designation number (optional). ²See Kind Codes of USPTO Patent Documents at www.uspto.gov, MPEP 901.04 or follow the hyperlink from the title of the document to the intranet. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶

Applicant's unique citation designation number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to indicate here if English language Translation is attached.